

A novel TPC readout system based on readout chips for Si-pixel detectors

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Proposal for Generic Detector R&D for an Electron Ion Collider

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Proponents

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EIC Physics Relevance

SIDIS reactions in e-p, respectively e-A collisions

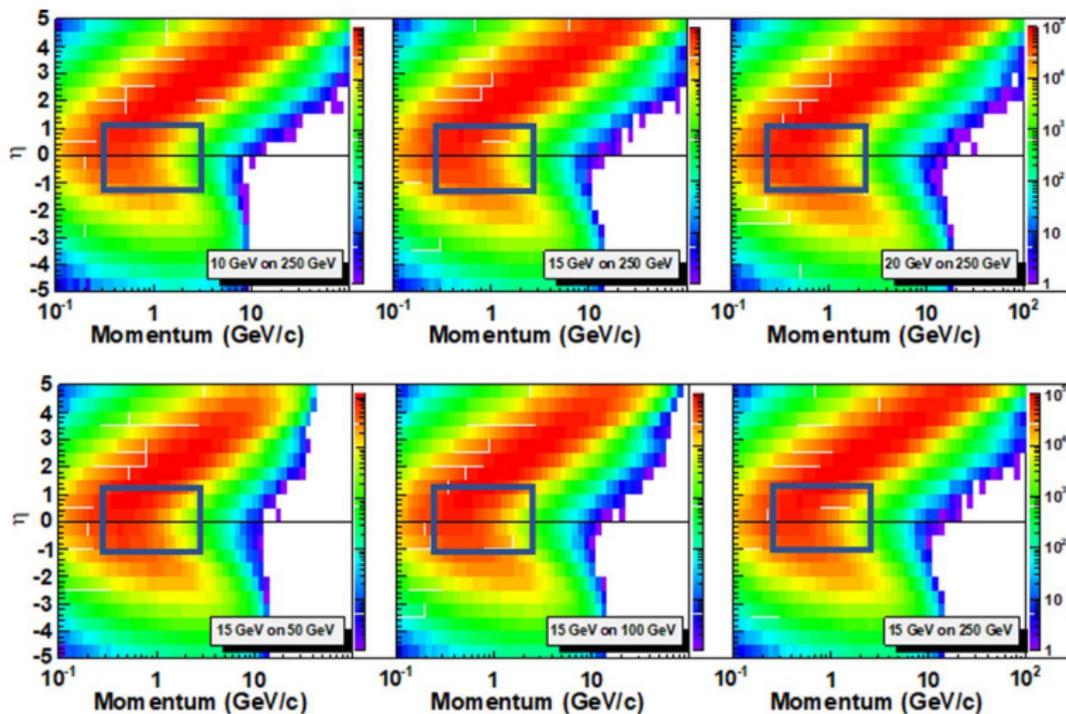
- ▶ Spin of the proton
- ▶ Fragmentation Functions (FF)
- ▶ Transverse Momentum Distributions (TMDs) by means of flavor tagging through hadron type
- ▶ Measuring Kaon asymmetries and cross sections
- ▶ Measuring strangeness Probability Distribution Functions (PDFs)

Require Particle Identification (PID) and separation over a wide range in pseudorapidity: $|\eta| < 3$

EIC Physics Relevance

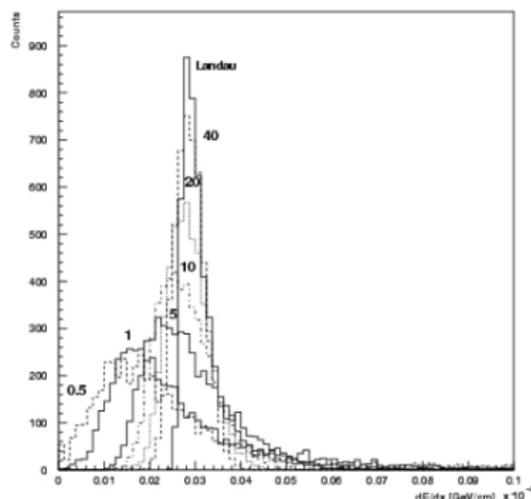
π^\pm kinematics in SIDIS, K^\pm and p^\pm show similar kinematics

$-\eta$ ← lepton beam → hadron beam $+\eta$



EIC Physics Relevance and a Time Projection Chamber

- ▶ Particle Identification (PID) in $|\eta| < 1$ desirable
- ▶ PID for low momenta up to about 3-4 GeV/c desirable
- ▶ Principle idea of a Time Projection Chamber (TPC):
combination of tracking and PID $\rightarrow \frac{dE}{dx}$ in a single detector
- ▶ TPC: Very well suited to perform PID tasks in mid-rapidities
- ▶ However: (dE/dx for 3 GeV e^- in Ar)



Charge vs Cluster Counting

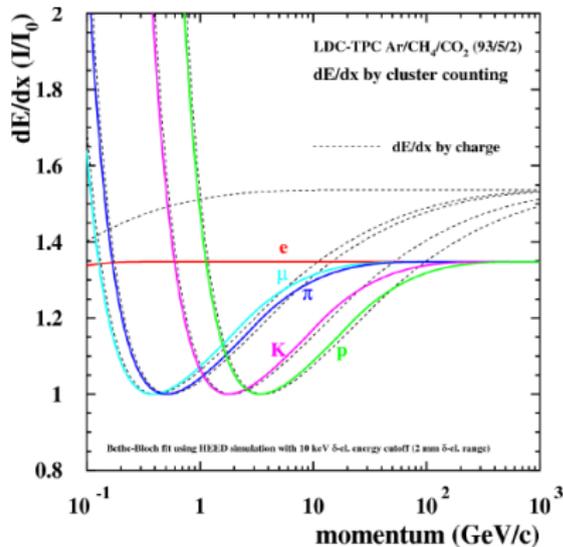
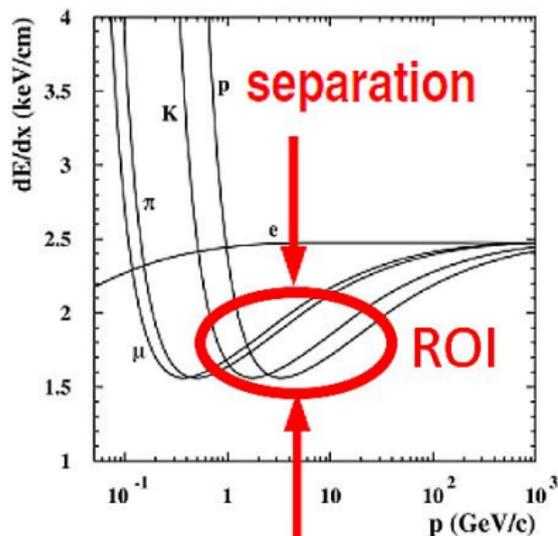
- ▶ Procedure most widely used: count charge and truncate mean → lowest $p\%$ (typically $p = 60 - 80$) of the pulse heights
 - ▶ Cut reduces effect of fluctuations due to long tail
 - ▶ Cut also removes fraction of track samples → worsens the ionization resolution
- ▶ Alternative: count number of clusters → complete suppression of Landau tail
 - ▶ Every cluster -big or small- has the same weight → Poissonian distribution with significantly smaller width
 - ▶ Better correlation and particle identification power

$$\text{separation power} = \frac{\text{separation}}{\text{resolution}}$$

- ▶ Improvement in pattern recognition and track fitting → better double hit/track resolution

Energy Loss via Bethe-Bloch

Compare energy loss obtained with charge counting and cluster counting¹

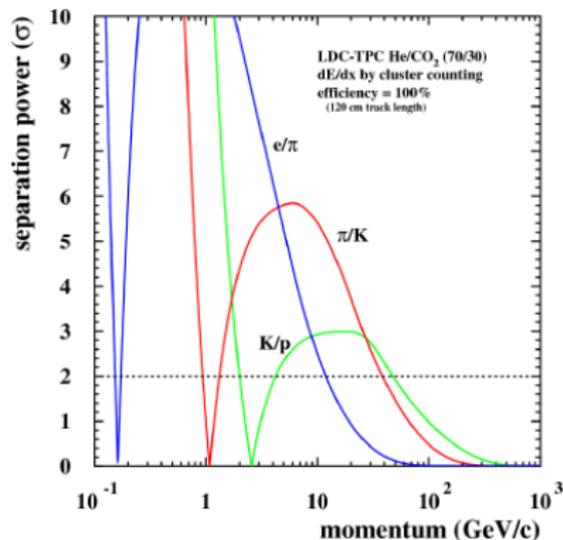
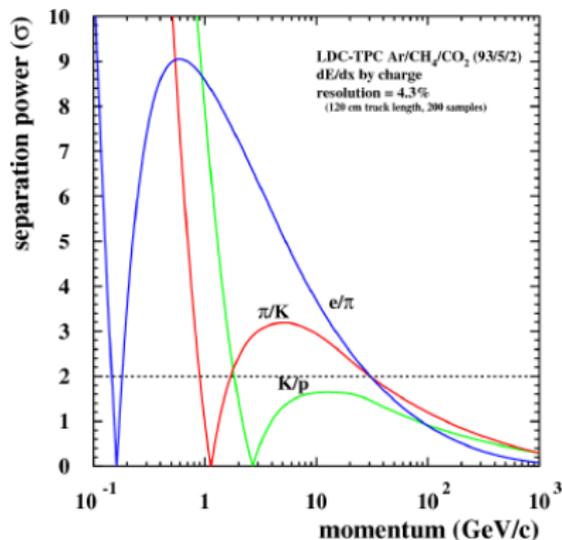


¹Based on calculations for the LDC-TPC read out with triple-GEM detectors, with Ar-CH₄-CO₂ (93-5-2) counting gas and 120 cm track lengths.



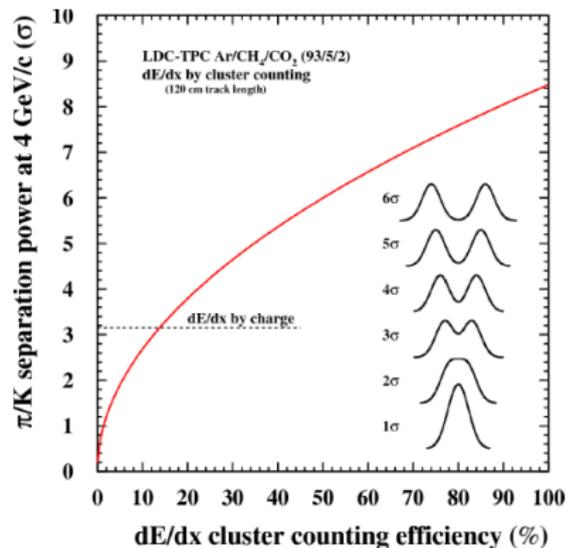
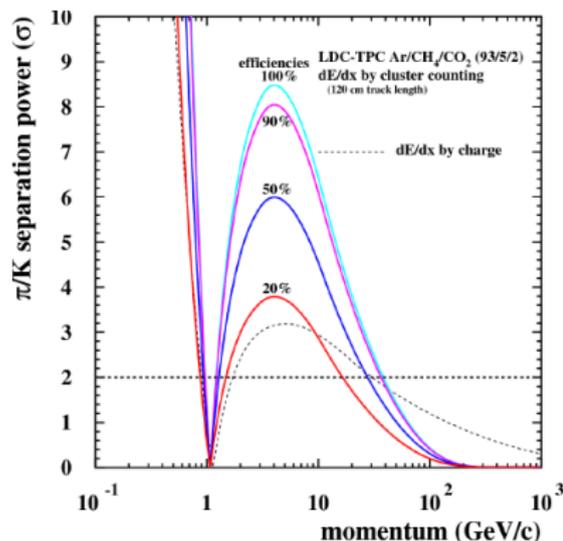
Separation Power

Compare separation power obtained with charge counting (LDC-TPC gas) and cluster counting (He-CO₂ gas: 70-30)



Separation Power with Inefficiencies

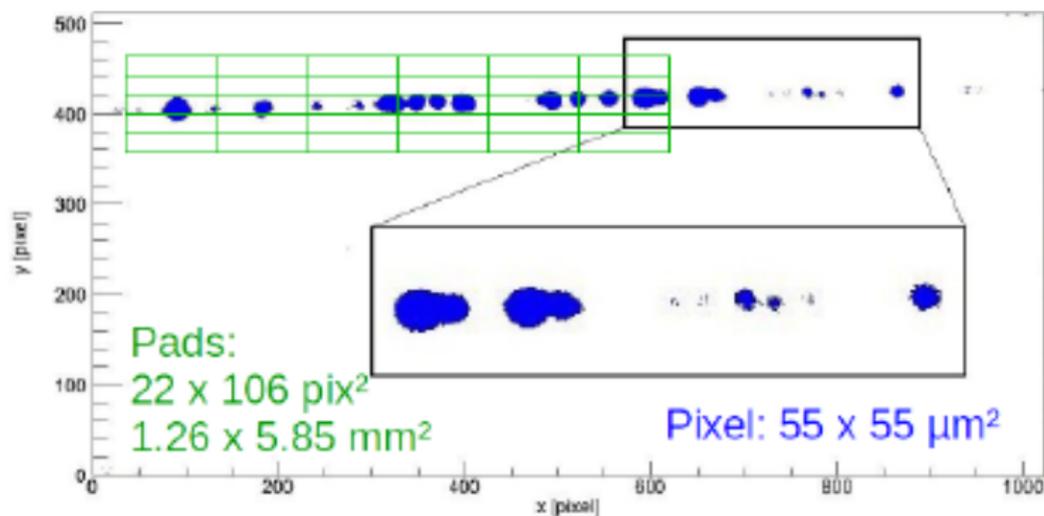
Compare separation power obtained with charge counting and cluster counting with inefficiencies²



²100% efficiency is virtually impossible \rightarrow transverse diffusion will result in merging of clusters.

How to Count Clusters

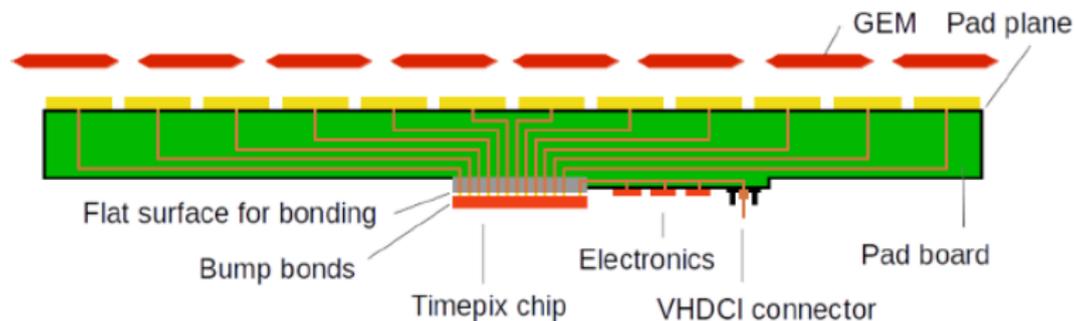
- ▶ Provide readout with sufficiently high granularity



→ TimePix ASIC with appropriate pad size

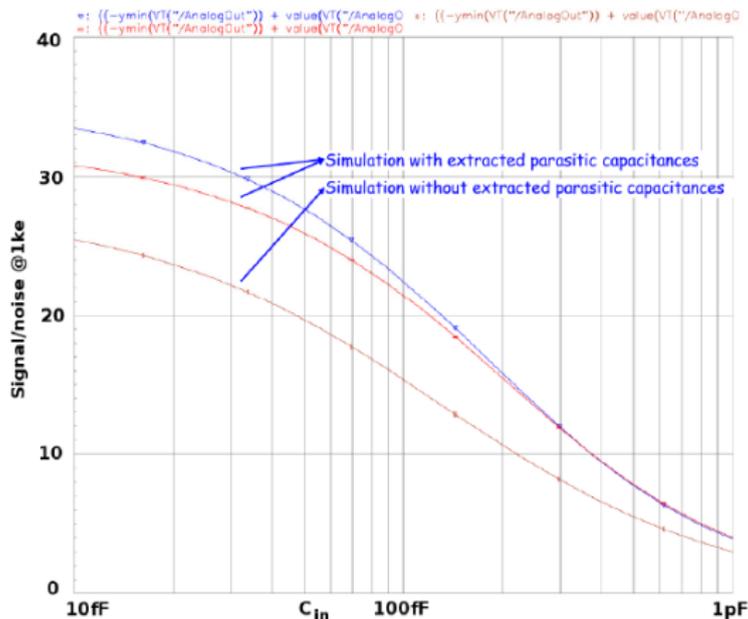
Proposed Studies

- ▶ Based on TimePix ASIC
 - ▶ TDC readout per channel in highly integrated package
 - ▶ $256 \times 256 = 65,536$ pixels, pixel pitch $55 \mu\text{m} \times 55 \mu\text{m}$
 - ▶ Each pixel can record either time of arrival or charge collected (ToT)
- ▶ Combine TimePix with traditional PCB
 - ▶ Larger pad size, pitch: $\sim 300 \mu\text{m}$
 - ▶ Connections from pads routed through PCB to ASIC \rightarrow bump bonded to PCB surface



Challenges

- ▶ TimePix optimized for low input capacitance (10-100 fF)
- ▶ TimePix chip with its small pixels to be connected to readout plane
- ▶ Routing on PCB between bump bond pads and charge collection pads is non-trivial

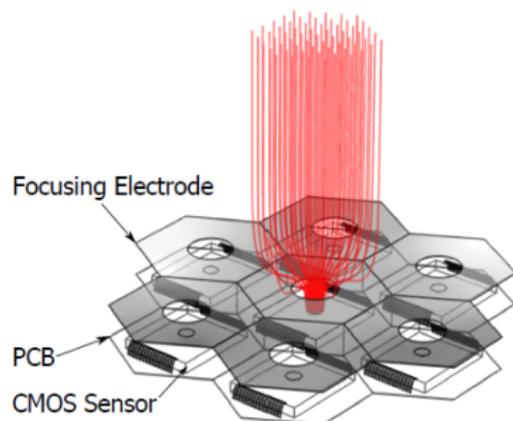


Advantages

- ▶ Perform cluster counting
- ▶ Footprint of readout much reduced
- ▶ Power consumption much reduced
- ▶ Significant decreased material budget in forward direction
- ▶ System significantly cheaper than traditional one
- ▶ System offers possibility to
 - ▶ reduce significantly size of pads
 - ▶ profit from increased precision but no need to go to extreme case of pad size of chip

R&D Program: First Year

- ▶ First existing setup with bump-bonded TimePix at DESY → test of system
- ▶ Development of simulation tools for optimizing pad size to adapt to compact sized EIC-TPC
- ▶ Development of routing technologies in small setup → focusing electrodes
- ▶ Optimize connection techniques
- ▶ Work toward proof-of-principle experiment



R&D Program: Second Year

- ▶ Production of PCB with \mathcal{O} (few 1000) channels
- ▶ Test with large TPC prototype
- ▶ Investigate different PCB technologies (ceramics, Si)
- ▶ Investigate alternative pixel readout electronics (FEI4, Topmetal)

Deliverables

- ▶ Establish utilization of a TimePix based readout for gaseous chambers
 - ▶ Establish connection technology to successfully bond TimePix to readout plane
 - ▶ Develop routing design for optimized signal transport for very low charge signals (10^3 - 10^5 electrons) confirmed by simulations and experiments
 - ▶ Establish alternative technologies (e.g. ceramics based) for pad planes for possible improved mechanical and thermal properties
- ▶ For year 2 continuation of the project: produce a nominal TPC module for EIC detector with 5000 charge collecting pads connected to 1-3 TimePix ASIC and verify in test beam

Funding Request

Year 1 cost item	DESY	Bonn	SBU	Sum
Grad. student	(1/2) \$25k	(1/2) \$25k	\$48.5k	\$98.5k
Board production	\$10k	\$20k	\$10k	\$40k
TimePix chip	-	-	\$5k	\$5k
Travel costs	-	-	\$5k	\$5k
Total request	\$35k	\$45k	\$68.5k	\$148.5k

Reduced funding scenarios:

Nominal - 20%

Reduction would affect board production and the acquisition of the TimePix chip → 50% cut on board production, cancellation of TimePix acquisition

Nominal - 40%

Reduction would affect board production and acquisition of the TimePix chip → No hardware available